



Manager Package Development

Job description

You will ably support the technical aspect of New Product Introduction (NPI) Projects at Outsource Assembly and Test (OSAT) subcontractors within the organization.

In your new role you will:

- Supports the **technical aspect of New Product Introduction (NPI)** Projects at Outsource Assembly and Test (OSAT) subcontractors
- Meet customer requirements in terms of timeline, cost and quality.
- **Risk assessment and mitigation of NPI Projects**
- Resolution of **manufacturability and reliability issues** of NPI Projects

Profile

You are best equipped for this task if you have:

- Bachelor/Master's Degree in Engineering/Science
- At least **10 years** experience in **semiconductor packaging industry** involving **process engineering and package development**
- Experience in specifying design and materials to meet requirements of new packages & products at Outsourced Assembly and Test(OSAT)subcontractors
- Package development experience in **T O, QFN, Cu Clip, SOIC, QFP, FlipChip, and Laminate based Packages**
- Knowledgeable in industry standards for package reliability test and qualifications
- Familiar with failure analysis techniques
- Working knowledge of **DFMEA and PFMEA** during design and development phases and ability to create strategies to mitigate risks
- User of **AutoCAD software**

At a glance

Location: **Manila (Philippines)**
Job ID: **358305**
Start date: **as soon as possible**
Entry level: **5+ years**
Type: **Full time**
Contract: **Permanent**

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- User of statistical analysis software (ex. **JMP/Minitab**)

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